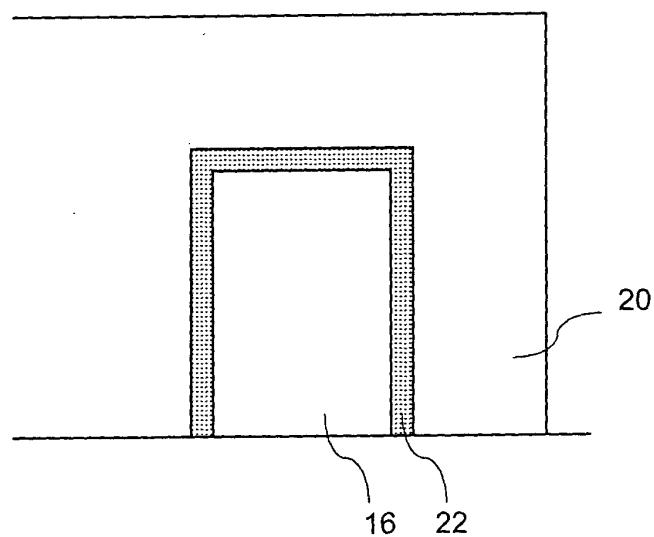
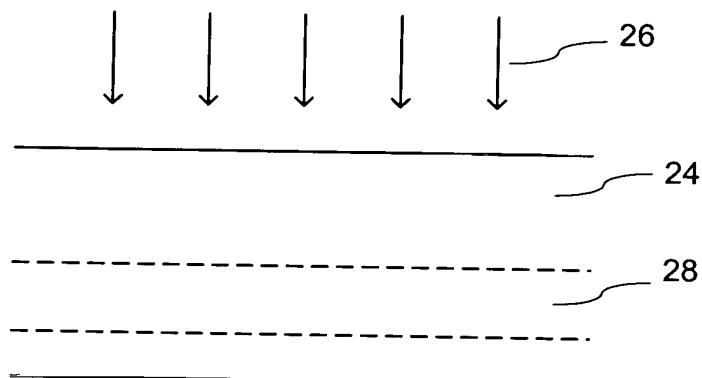


**Figure 1**  
**Prior Art**

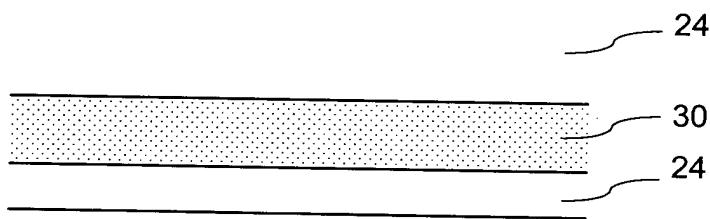


**Figure 2**  
**Prior Art**

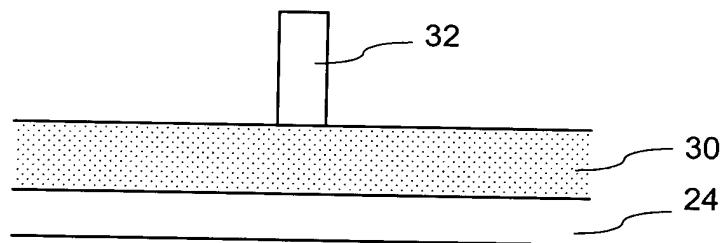
**Figure 3a**  
**Prior Art**



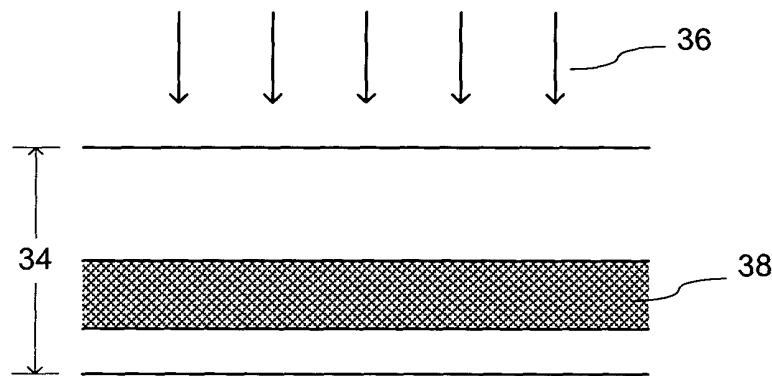
**Figure 3b**  
**Prior Art**



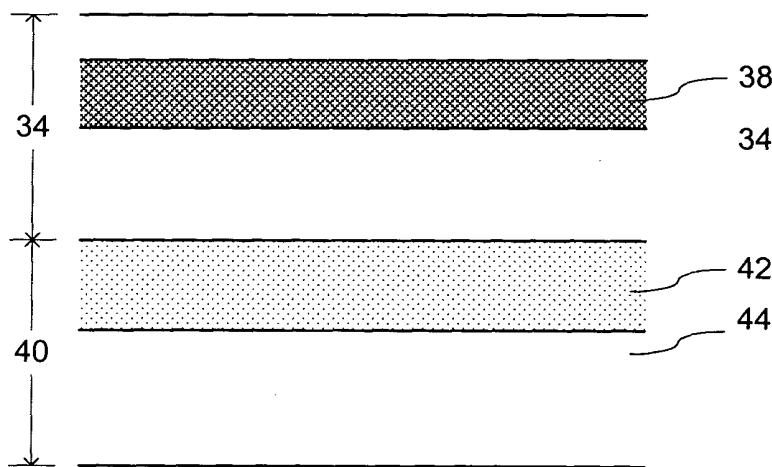
**Figure 3c**  
**Prior Art**



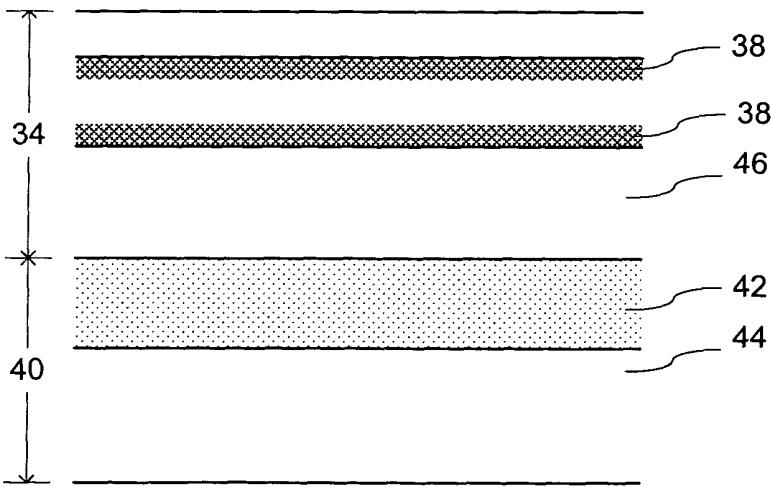
**Figure 4a**  
**Prior Art**



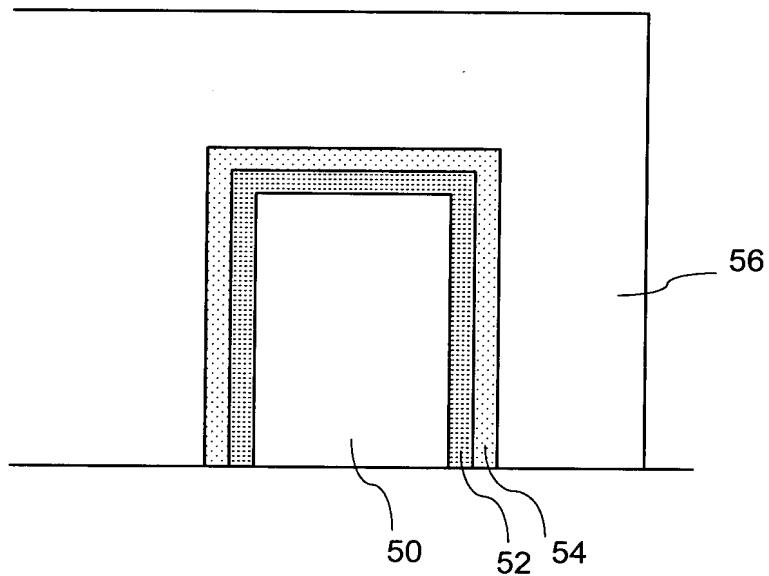
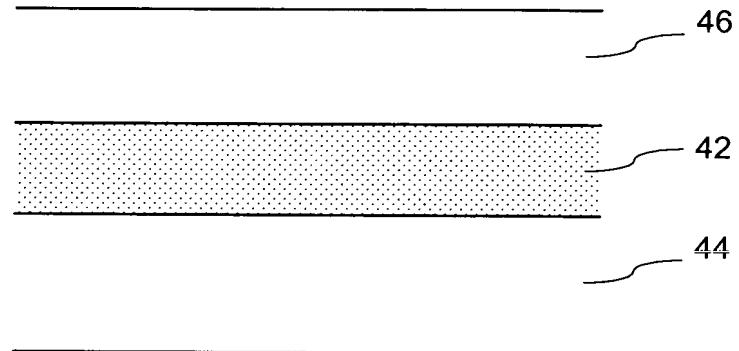
**Figure 4b**  
**Prior Art**



**Figure 4c**  
**Prior Art**

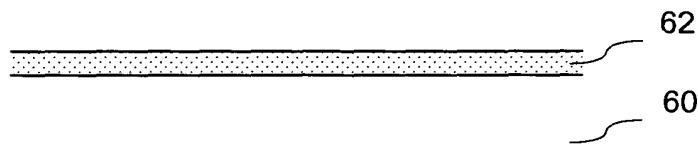


**Figure 4d**  
**Prior Art**

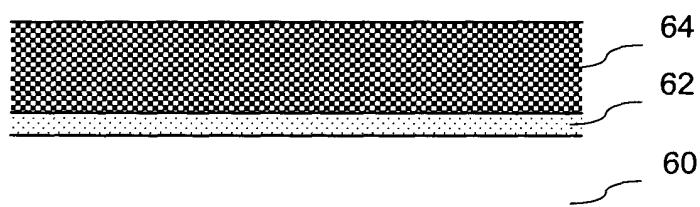


**Figure 5**

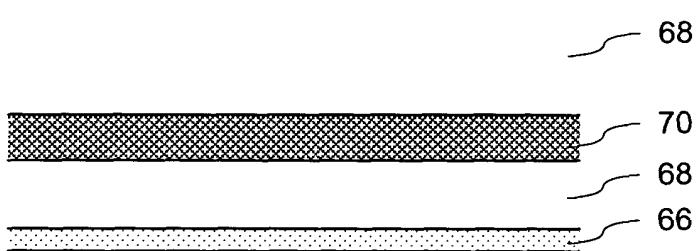
**Figure 6a**



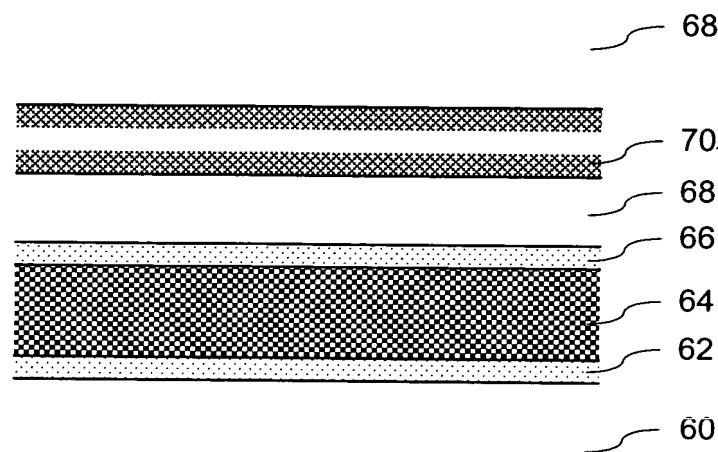
**Figure 6b**



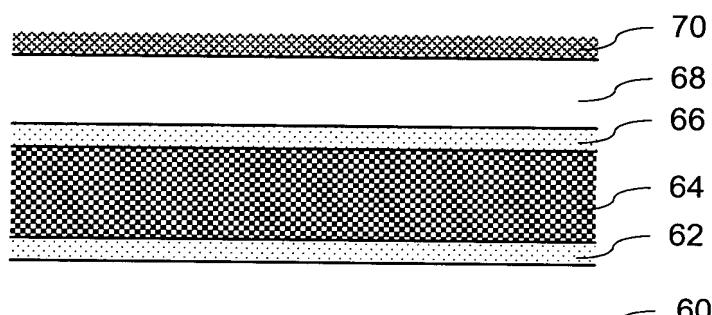
**Figure 6c**



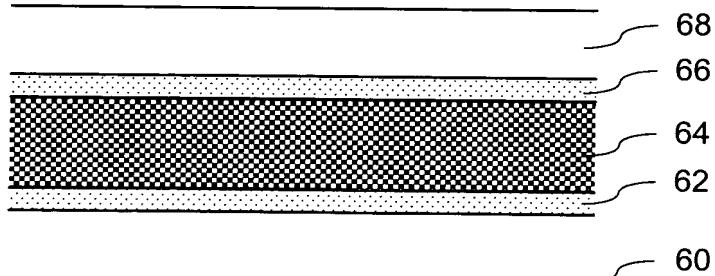
**Figure 6d**



**Figure 6e**



**Figure 6f**



SILICON INSULATING SUBSTRATE HAVING  
IMPROVED THERMAL CONDUCTIVITY AND  
METHOD OF ITS FORMATION  
Inventors: Qi Xiang et al.  
Attorney: Ronald Cosick - 039153-0675  
FOLEY & LARDNER - (310) 277-2223  
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Figure 6g

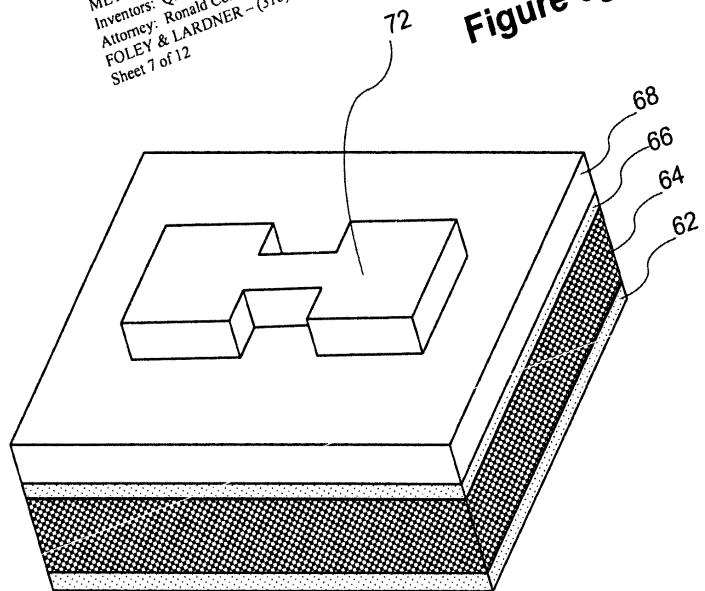
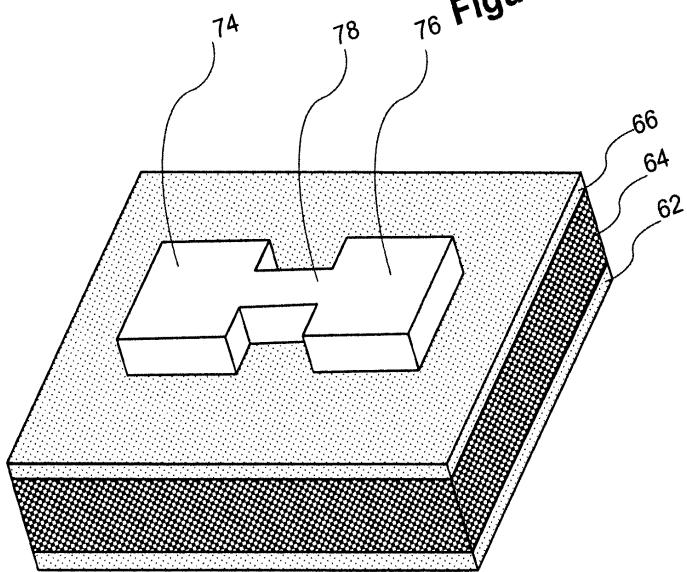
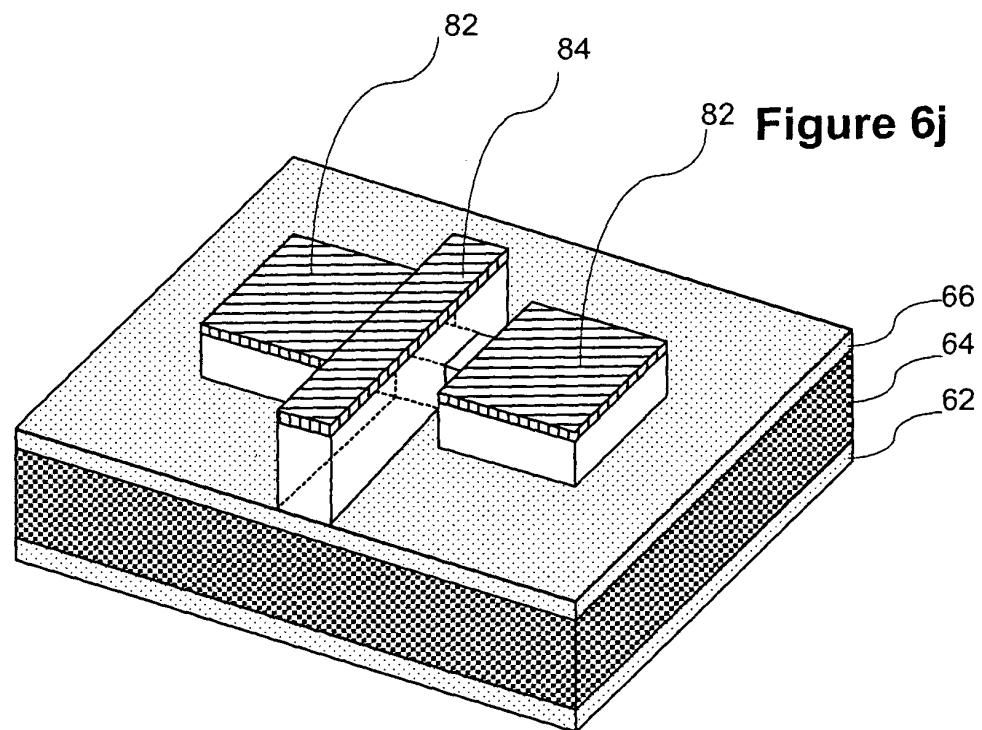
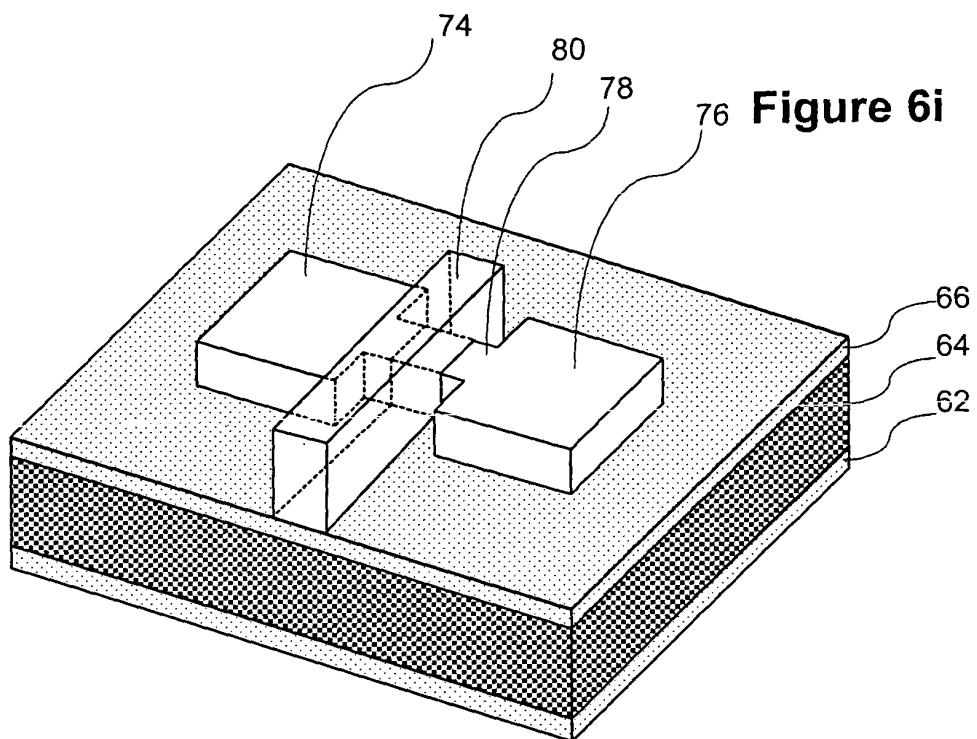
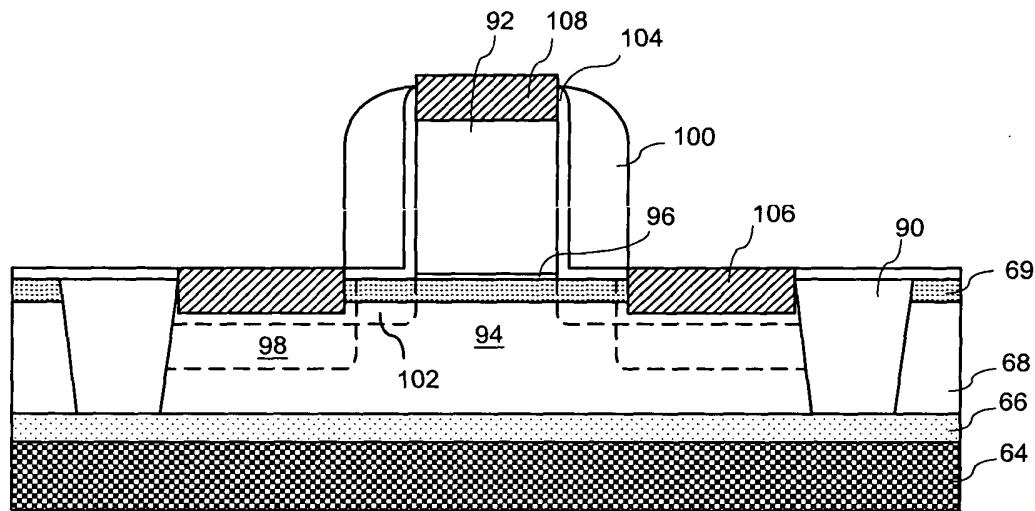


Figure 6h

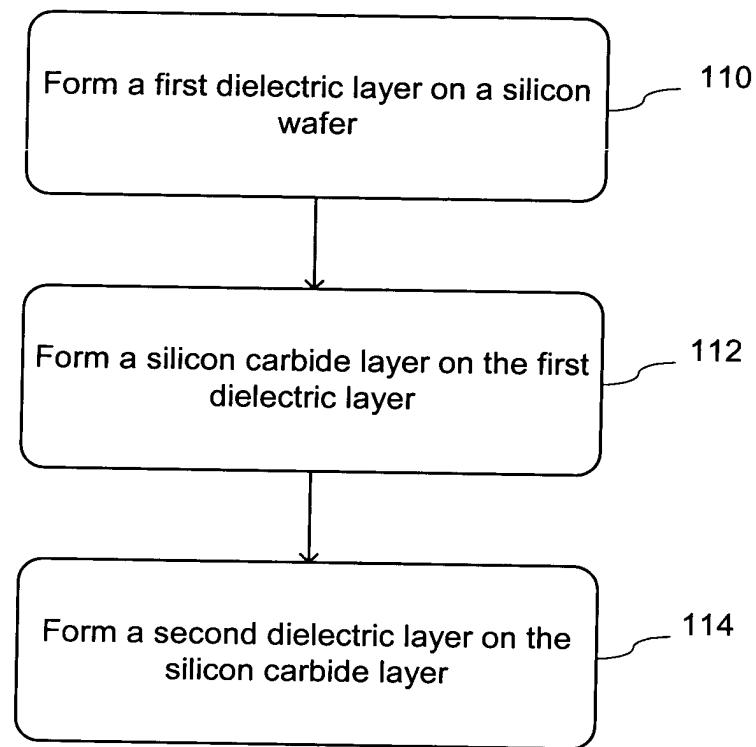




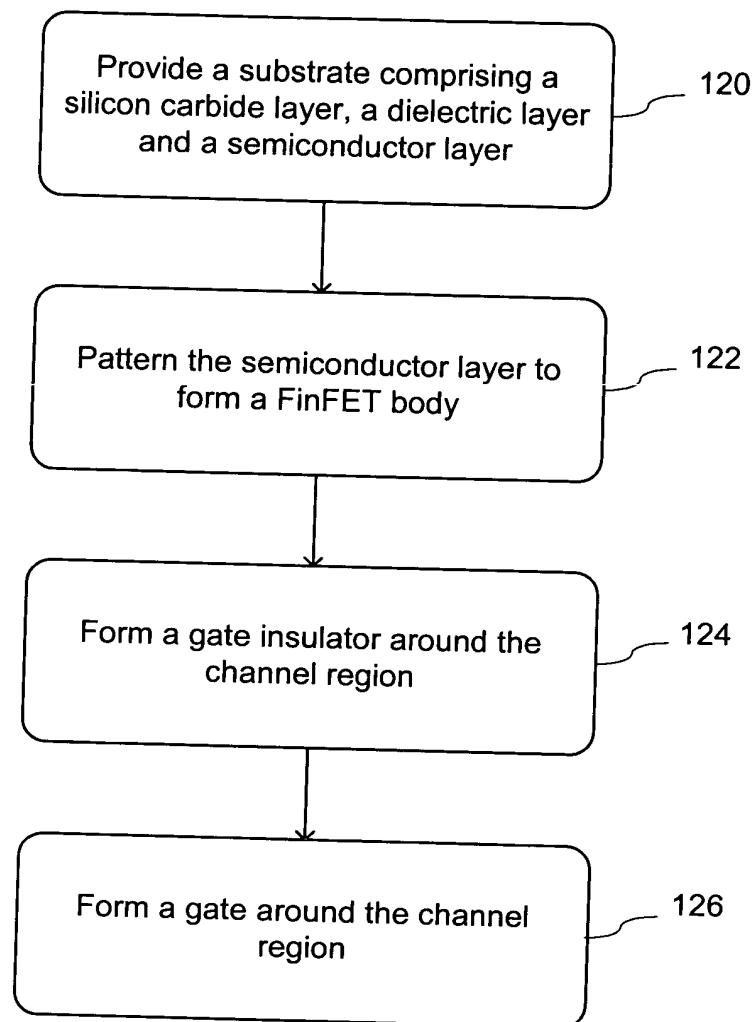
SILICON ON INSULATOR SUBSTRATE HAVING  
IMPROVED THERMAL CONDUCTIVITY AND  
METHOD OF ITS FORMATION  
Inventors: Qi Xiang et al.  
Attorney: Ronald Coslick - 039153-0675  
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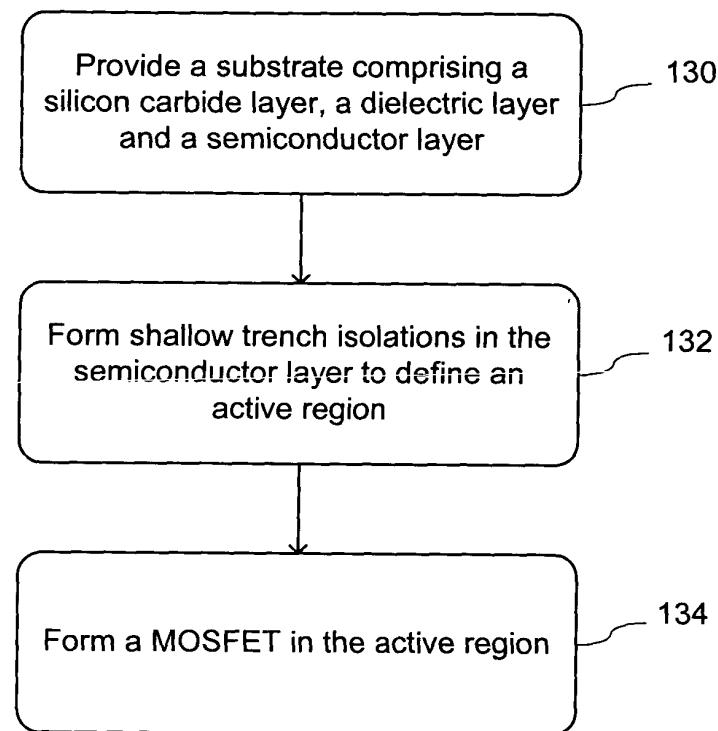
**Figure 7**



**Figure 8**



**Figure 9**



**Figure 10**